

(TIM-GAP) Thermally Conductive Gap filling Sheet materials

Properties	Units	1101	1102	1103	1106	HTC-11	SOFT	Ultra Soft	NS
Type		Silicone	Silicone	Silicone	Silicone	Silicone	Silicone	Silicone	Non-Silicone
Thermal Conductivity	W/m.°K	1.4	2.4	2.8	6.0	11.0	1.3	1.5	1.6
Thermal Resistance	°C-In/W	2.1(0.1")	1.7(0.1")	1.1(0.08")	0.31(0.04")	0.22(0.06")	0.90(0.02")	0.99(0.08")	0.72(0.02")
Hardness	Shore 00	48	48	54	54	-	48	<5	53
Elongation	%	100	100	65	53	-	250	320	150
Volume Resistivity	Ohm-cm	10 ¹⁴	10 ¹⁴	10 ¹²	10 ¹²	10 ¹¹	10 ¹⁰	10 ¹³	10 ¹⁵
Max. Service Temperature	°C	200	200	200	200	200	200	200	110
Available Thickness	Inch	0.02-0.2	0.02-0.2	0.02-0.12	0.02-0.12	0.06,0.08,0.10	0.2-0.12	0.08-0.20	0.02,0.04,0.08

(TIM-LGF) Thermally Conductive Dispensable Liquid Gap Fillers

Properties	Units	2000	2001	2002	2004	418	418HTC	519
Type		Silicone	Silicone	Silicone Elec. Conductive	Silicone	Non-Silicone Putty	Non-Silicone Putty	Silicone Putty
Thermal Conductivity	W/m.°K	2.0	0.63	N/A	2.0	2.1	3.2	1.5
Volume Resistivity	Ohm-cm	10 ¹²	10 ¹⁵	0.09	10 ¹²	10 ¹²	10 ¹²	10 ¹²
Mix ratio/Cure Type		One part Heat cure	One part RT cure	One part RT cure	Two parts RT Cure	One part No Cure	One Part No Cure	One Part No Cure
Cure Time	Hours	½ hr @120°C	72 hrs @25°C	72 hrs. @25°C	24 hrs. @25°C	No Cure	No Cure	No Cure
Hardness	Shore 00/A	70(00)	40(A)	40(A)	70(00)	N/A	N/A	N/A
Max. Service Temperature	°C	250	260	260	200	200	200	250

(TIM-PAD) Thermally Conductive Pads

Properties	Units	1001	1002	1003	Gel Pad
Type		Silicone	Silicone	Silicone	Silicone
Thermal Conductivity	W/m.°K	1.1	1.6	3.0	1.6
Thermal Resistance	°C-In ² /W	0.51(0.08")	0.55(0.08")	0.30(0.08")	0.35(0.01")
Hardness.	Shore 00	86	93	84	49
Elongation	%	<2	<2	<2	15
Volume Resistivity	Ohm-cm	10 ¹⁵	10 ¹⁵	10 ¹⁵	10 ¹⁵
Max. Service Temperature	°C	200	200	200	150
Available Thickness	Inch	0.006,.0.008 0.012	0.006,.0.008 0.012	0.006,.0.008 0.018,0.034	0.010